

View Online at <https://aerobasegroup.com/nsn/6340-01-219-6258>

Semiconductor Material:

Copper

Special Features:

Flex circuit laminated using 1oz copper per qq-c-576 with .001 thk.Polyamide per mil-p-46112.Laminates to be bonded using thermosetting acrylic adhesive or equal.Total thickness to be .015 max.Consist of flexprint 1, stiffener 1; part of fire warning system

Functional Description:

B-1b aircraft

Fsc Application Data:

Aircraft accessory equipment

Shelf Life:

N/a

Unit Of Measure:

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Demilitarization:

No

Fiig:

T278-m